

Title (en)

Chemical copper plating solution.

Title (de)

Stromlose Kupferplattierlösung.

Title (fr)

Bain de dépôt chimique de cuivre.

Publication

**EP 0179212 A2 19860430 (EN)**

Application

**EP 85109921 A 19850807**

Priority

- JP 20044584 A 19840927
- JP 27330384 A 19841226

Abstract (en)

There is disclosed a chemical copper plating solution containing a copper salt, a complexing agent, a reducing agent and a pH adjustor which further comprises at least one of the following Groups (A) and (B); Group (A); at least one non-ionic surface active agent selected from the group consisting of a non-ionic surface active agent having the formula: <CHEM> (wherein m1 and n1 each represent an integer of 1 or more) and a non-ionic surface active agent having formula: <CHEM> (wherein m2 and n2 each represent an integer of 1 or more), and at least one compound selected from the group consisting of 1,10-phenanthroline, a 1,10-phenanthroline derivative, 2,2 min -dipyridyl, 2,2 min -biquinoline and a water-soluble cyan compound; Group (B); an organic sulfur compound and an ethyleneamine compound.

IPC 1-7

**C23C 18/40**

IPC 8 full level

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CPC (source: EP)

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